

## FEATURES

- Member of the Texas Instruments Widebus+™ Family
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This device contains eight independent noninverting buffers and a 16-bit noninverting bus transceiver and D-type latch designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH32973 is particularly suitable for demultiplexing an address/data bus into a dedicated address bus and dedicated data bus. The device is used where there is asynchronous bidirectional communication between the A and B data bus, and the address signals are latched and buffered on the Q bus. The control-function implementation minimizes external timing requirements.

This device can be used as one 8-bit buffer, two 8-bit transceivers, and two 8-bit latches or one 8-bit buffer, one 16-bit transceiver, and one 16-bit latch. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The transceiver output-enable ( $\overline{TOE}$ ) input can be used to disable the transceivers so that the A and B buses effectively are isolated.

When the latch-enable (LE) input is high, the Q outputs follow the data (A) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the A inputs. The latch output-enable ( $\overline{LOE}$ ) input can be used to place the nine Q outputs in either a normal logic state (high or low logic level) or the high-impedance state. In the high-impedance state, the Q outputs neither drive nor load the bus lines significantly.  $\overline{LOE}$  does not affect internal operations of the latch. Old data can be retained or new data can be entered while the Q outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{LOE}$  and  $\overline{TOE}$  should be tied to  $V_{CC}$  through pullup resistors; the minimum values of the resistors are determined by the current-sinking capability of the drivers.

The eight independent noninverting buffers perform the Boolean function  $Y = D$  and are independent of the state of DIR,  $\overline{TOE}$ , LE, and  $\overline{LOE}$ .

The A and B I/Os and D inputs have bus-hold circuitry. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

## ORDERING INFORMATION

$T_A$	PACKAGE (1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	LFBGA - GKE	Tape and reel	SN74ALVCH32973KR	ACH973
	LFBGA - ZKE (Pb-free)		74ALVCH32973ZKER	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



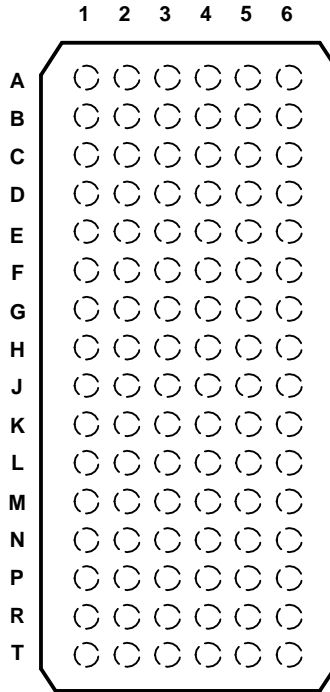
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**SN74ALVCH32973**  
**16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH**  
**WITH EIGHT INDEPENDENT BUFFERS**

SCES436C–APRIL 2003–REVISED SEPTEMBER 2004

**GKE OR ZKE PACKAGE**  
**(TOP VIEW)**



**TERMINAL ASSIGNMENTS**

	1	2	3	4	5	6
<b>A</b>	1A1	D1	1 $\overline{TOE}$	1DIR	1B1	1Q1
<b>B</b>	1A2	Y1	GND	GND	1B2	1Q2
<b>C</b>	1A3	D2	V <sub>CC</sub>	V <sub>CC</sub>	1B3	1Q3
<b>D</b>	1A4	Y2	GND	GND	1B4	1Q4
<b>E</b>	1A5	D3	GND	GND	1B5	1Q5
<b>F</b>	1A6	Y3	V <sub>CC</sub>	V <sub>CC</sub>	1B6	1Q6
<b>G</b>	1A7	D4	GND	GND	1B7	1Q7
<b>H</b>	1A8	Y4	1LE	1 $\overline{LOE}$	1B8	1Q8
<b>J</b>	2A1	D5	2 $\overline{TOE}$	2DIR	2B1	2Q1
<b>K</b>	2A2	Y5	GND	GND	2B2	2Q2
<b>L</b>	2A3	D6	V <sub>CC</sub>	V <sub>CC</sub>	2B3	2Q3
<b>M</b>	2A4	Y6	GND	GND	2B4	2Q4
<b>N</b>	2A5	D7	GND	GND	2B5	2Q5
<b>P</b>	2A6	Y7	V <sub>CC</sub>	V <sub>CC</sub>	2B6	2Q6
<b>R</b>	2A7	D8	GND	GND	2B7	2Q7
<b>T</b>	2A8	Y8	2LE	2 $\overline{LOE}$	2B8	2Q8

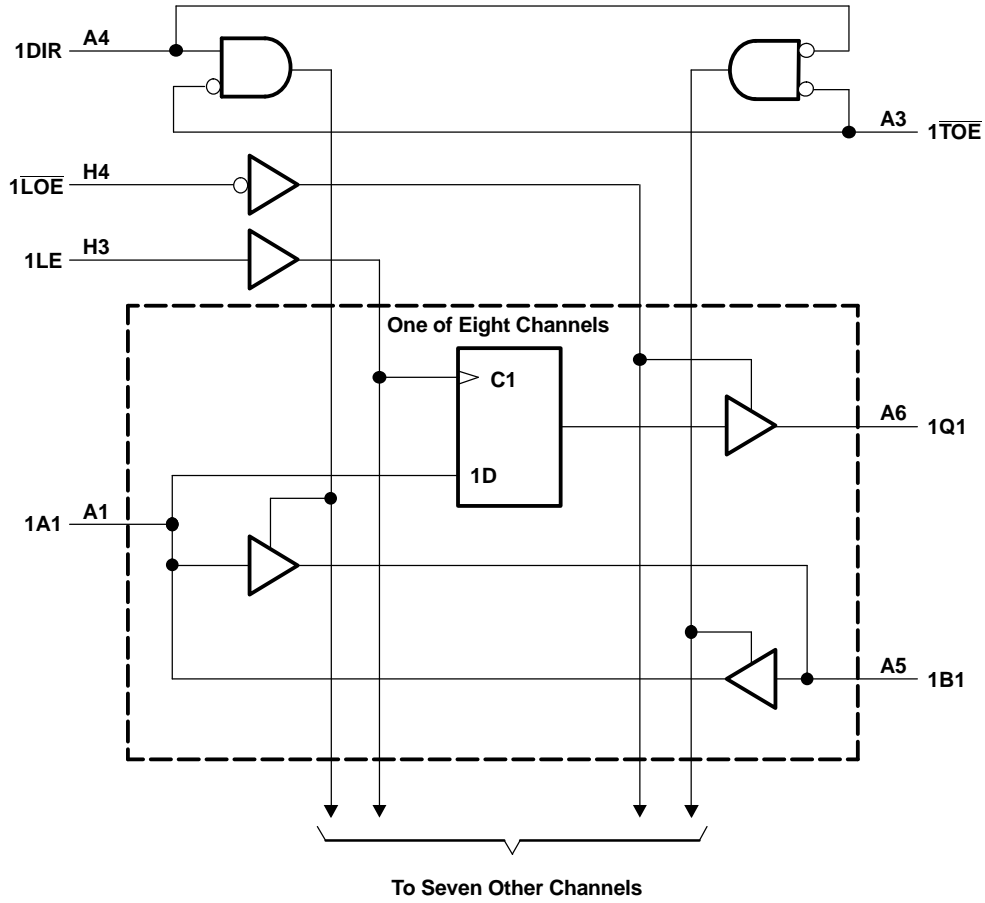
**FUNCTION TABLES**

INPUTS		OPERATION
$\overline{TOE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	A bus and B bus isolation

INPUTS			OUTPUT Q
$\overline{LOE}$	LE	A	
L	H	H	H
L	H	L	L
L	L	X	Q <sub>0</sub>
H	X	X	Z

INPUT D	OUTPUT Y
L	L
H	H

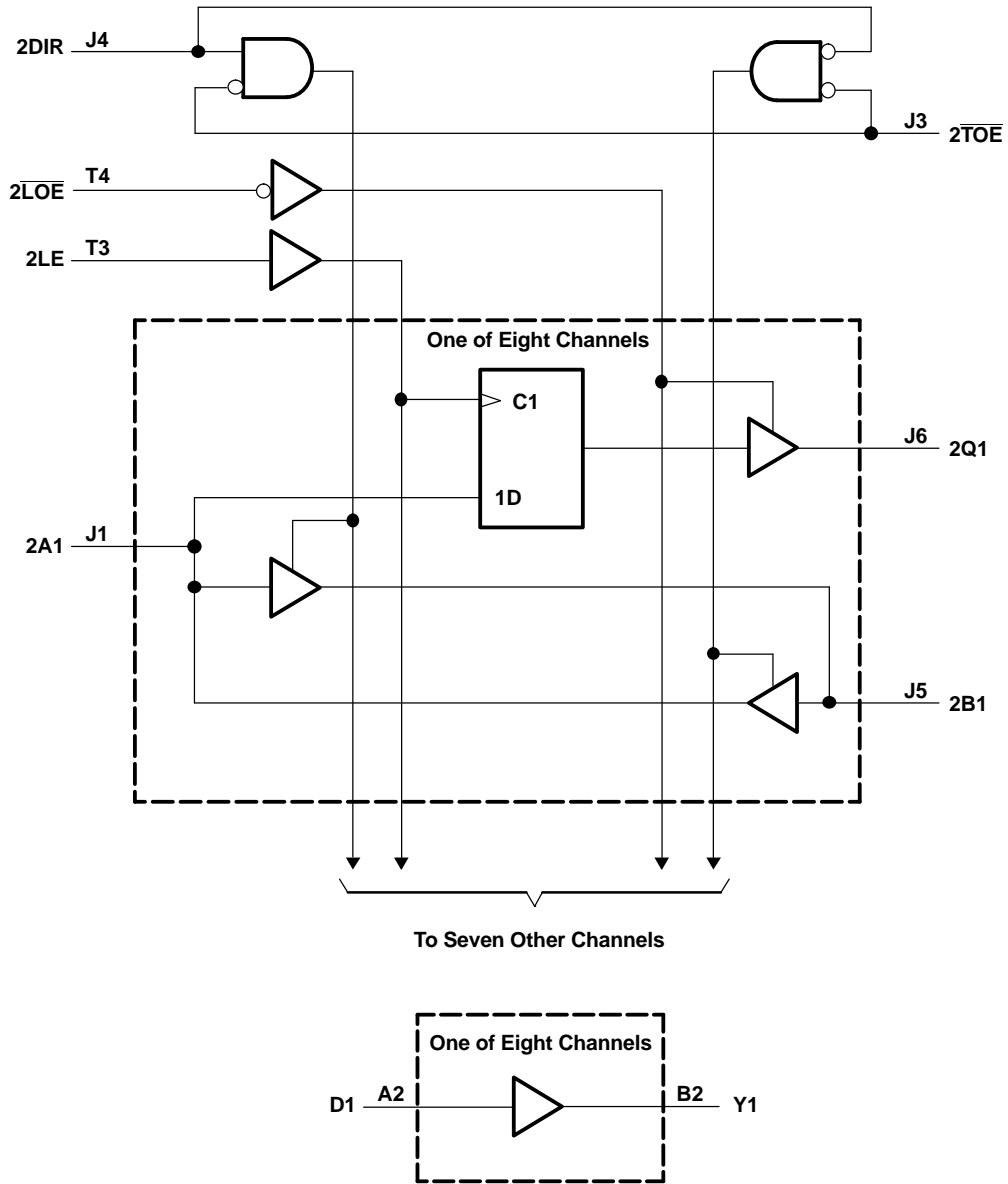
**LOGIC DIAGRAM (POSITIVE LOGIC)**



**SN74ALVCH32973**  
**16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH**  
**WITH EIGHT INDEPENDENT BUFFERS**

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**LOGIC DIAGRAM (POSITIVE LOGIC)**



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range	Except I/O and D input ports <sup>(2)</sup>		V
		I/O and D input ports <sup>(2)(3)</sup>		
$V_O$	Output voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		-50 mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50 mA
$I_O$	Continuous output current			±50 mA
	Continuous current through each $V_{CC}$ or GND			±100 mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	GKE/ZKE package		40 °C/W
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	1.65	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	0.8	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$	-4	mA
		$V_{CC} = 2.3\text{ V}$	-12	
		$V_{CC} = 2.7\text{ V}$	-12	
		$V_{CC} = 3\text{ V}$	-24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$	4	mA
		$V_{CC} = 2.3\text{ V}$	12	
		$V_{CC} = 2.7\text{ V}$	12	
		$V_{CC} = 3\text{ V}$	24	
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
$T_A$	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74ALVCH32973

## 16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH WITH EIGHT INDEPENDENT BUFFERS

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### ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -6 mA	2.3 V	2			
	I <sub>OH</sub> = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I <sub>OH</sub> = -24 mA	3 V	2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2			V
	I <sub>OL</sub> = 4 mA	1.65 V	0.45			
	I <sub>OL</sub> = 6 mA	2.3 V	0.4			
	I <sub>OL</sub> = 12 mA	2.3 V	0.7			
		2.7 V	0.4			
	I <sub>OL</sub> = 24 mA	3 V	0.55			
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5			μA
I <sub>BHL</sub> <sup>(2)</sup>	V <sub>I</sub> = 0.57 V	1.65 V	25			μA
	V <sub>I</sub> = 0.7 V	2.3 V	45			
	V <sub>I</sub> = 0.8 V	3 V	75			
I <sub>BHH</sub> <sup>(3)</sup>	V <sub>I</sub> = 1.07 V	1.65 V	-25			μA
	V <sub>I</sub> = 1.7 V	2.3 V	-45			
	V <sub>I</sub> = 2 V	3 V	-75			
I <sub>BHLO</sub> <sup>(4)</sup>	V <sub>I</sub> = 0 to V <sub>CC</sub>	1.95 V	200			μA
		2.7 V	300			
		3.6 V	500			
I <sub>BHHO</sub> <sup>(5)</sup>	V <sub>I</sub> = 0 to V <sub>CC</sub>	1.95 V	-200			μA
		2.7 V	-300			
		3.6 V	-500			
I <sub>OZ</sub> <sup>(6)</sup>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	60			μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750			μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3			pF
	D					
C <sub>io</sub>	A ports	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V			pF
	B ports					
C <sub>o</sub>	Q	V <sub>O</sub> = V <sub>CC</sub> or GND	3			pF

- (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.
- (2) The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>IL</sub> max.
- (3) The bus-hold circuit can source at least the minimum high sustaining current at V<sub>IH</sub> min. I<sub>BHH</sub> should be measured after raising V<sub>IN</sub> to V<sub>CC</sub> and then lowering it to V<sub>IH</sub> min.
- (4) An external driver must source at least I<sub>BHLO</sub> to switch this node from low to high.
- (5) An external driver must sink at least I<sub>BHHO</sub> to switch this node from high to low.
- (6) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration, LE high	2		2		2		ns
$t_{su}$	Setup time, data before LE↓	0.9		0.9		0.9		ns
$t_h$	Hold time, data after LE↓	0.9		0.9		0.9		ns

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX		
$t_{pd}$	D	Y	2.2	0.5	3.2	0.5	3	ns	
	A	Q	2.2	0.5	3.2	0.5	3		
	LE		2.8	0.5	3.3	0.5	3		
	A or B	B or A	2.2	0.5	3.2	0.5	3		
$t_{en}$	$\overline{LOE}$	Q	2.9	0.7	4.9	0.7	4.7	ns	
	$\overline{TOE}$	A or B	3	0.7	4.6	0.7	4.4		
	DIR		3.4	0.7	4.9	0.7	4.7		
$t_{dis}$	$\overline{LOE}$	Q	2.8	0.5	4.3	0.5	4.1	ns	
	$\overline{TOE}$	A or B	3.2	0.5	4.3	0.5	4.1		
	DIR		3.4	0.5	4.9	0.5	4.7		

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**OPERATING CHARACTERISTICS<sup>(1)</sup>**

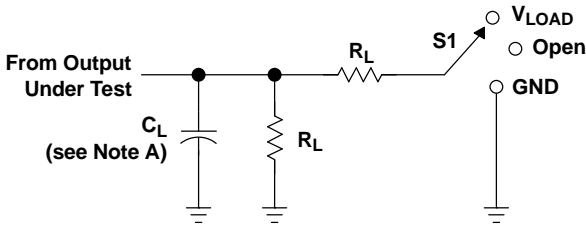
T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
			TYP	TYP	TYP	
C <sub>pd</sub> <sup>(2)</sup> (each output)	Power dissipation capacitance	A outputs enabled, Q outputs disabled, one A output switching One f <sub>A</sub> = 10 MHz, One f <sub>B</sub> = 10 MHz, TOE = GND, LOE = V <sub>CC</sub> , DIR = GND, C <sub>L</sub> = 0 pF	12	14	19	pF
		B outputs enabled, Q outputs disabled, one B output switching One f <sub>A</sub> = 10 MHz, One f <sub>B</sub> = 10 MHz, TOE = GND, LOE = V <sub>CC</sub> , DIR = GND, C <sub>L</sub> = 0 pF	12	14	21	
		Q outputs enabled, A and B I/Os isolated, one Q output switching One f <sub>A</sub> = 10 MHz, One f <sub>LE</sub> = 20 MHz, One f <sub>Q</sub> = 10 MHz, TOE = V <sub>CC</sub> , LOE = GND, C <sub>L</sub> = 0 pF	11	13	19	
		One Y output switching, A and B I/Os isolated, Q outputs disabled One f <sub>D</sub> = 10 MHz, One f <sub>Y</sub> = 10 MHz, TOE = V <sub>CC</sub> , LOE = V <sub>CC</sub> , C <sub>L</sub> = 0 pF	7	8	12	
C <sub>pd</sub> <sup>(Z)</sup>	Power dissipation capacitance	A and B I/Os isolated, Q outputs disabled, one LE and one A data input switching One f <sub>A</sub> = 10 MHz, One f <sub>LE</sub> = 20 MHz, f <sub>Q</sub> not switching, TOE = V <sub>CC</sub> , LOE = V <sub>CC</sub> , C <sub>L</sub> = 0 pF	4	5	11	pF
C <sub>pd</sub> <sup>(3)</sup> (each LE)	Power dissipation capacitance	A and B I/Os isolated, Q outputs disabled, one LE input switching f <sub>A</sub> not switching, One f <sub>LE</sub> = 20 MHz, f <sub>Q</sub> not switching, TOE = V <sub>CC</sub> , LOE = V <sub>CC</sub> , C <sub>L</sub> = 0 pF	6	7	9	pF

- (1) Total device C<sub>pd</sub> for multiple (m) outputs switching and (n) LE inputs switching = [m \* C<sub>pd</sub> (each output)] + [n \* C<sub>pd</sub> (each LE)]  
(2) C<sub>pd</sub> (each output) is the C<sub>pd</sub> for each data bit (input and output circuitry) when it operates at 10 MHz (Note: The LE is operating at 20 MHz in this test, but its I<sub>CC</sub> component has been subtracted).  
(3) C<sub>pd</sub> (each LE) is the C<sub>pd</sub> for the clock circuitry only when it operates at 20 MHz.



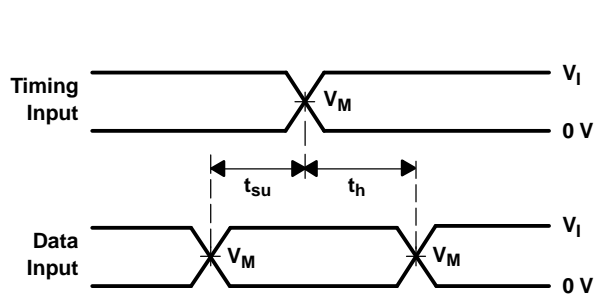
PARAMETER MEASUREMENT INFORMATION



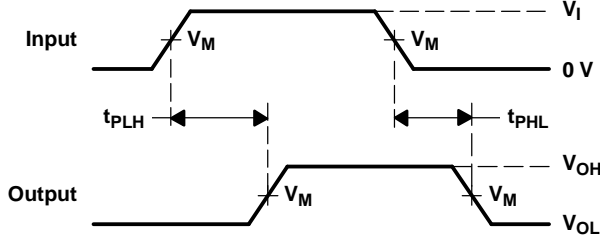
TEST	S1
$t_{pd}$ $t_{PLZ}/t_{PZL}$ $t_{PHZ}/t_{PZH}$	Open $V_{LOAD}$ GND

LOAD CIRCUIT

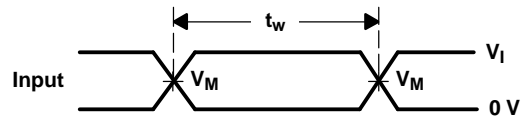
$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
1.8 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 V \pm 0.2 V$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3 V \pm 0.3 V$	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



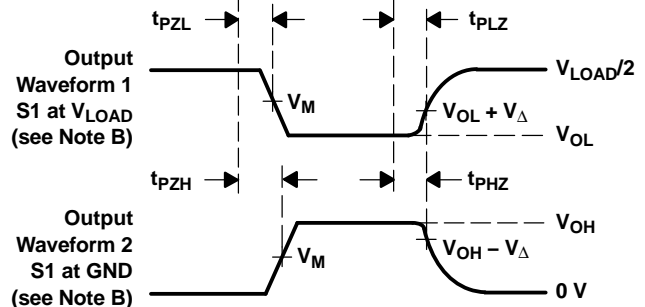
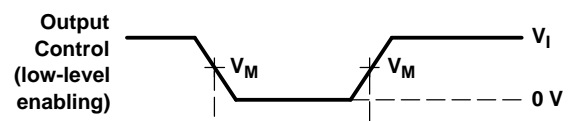
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
74ALVCH32973ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	ACH973	<a href="#">Samples</a>
SN74ALVCH32973KR	ACTIVE	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR	-40 to 85	ACH973	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH32973ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74ALVCH32973KR	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1

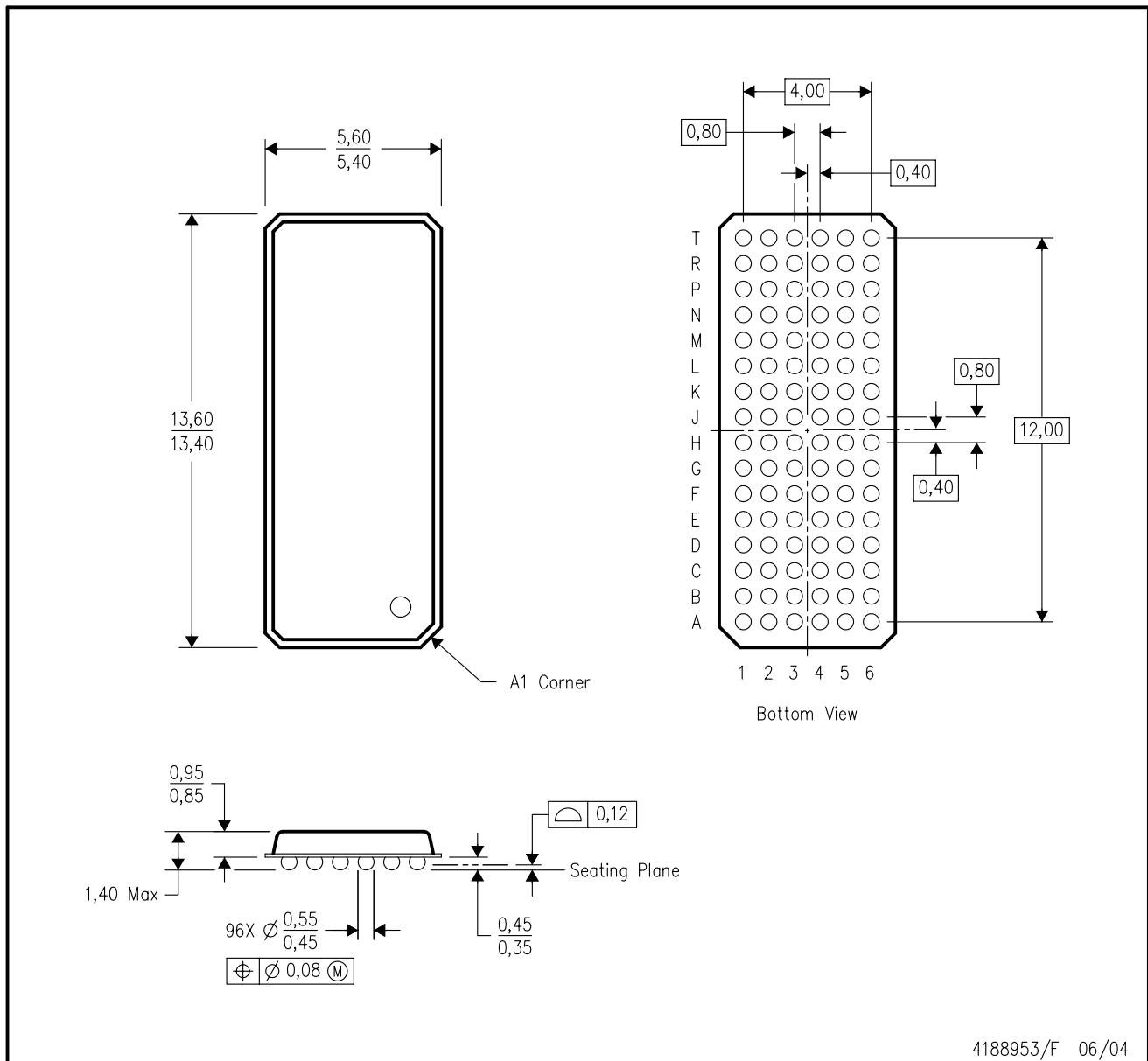
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH32973ZKER	LFBGA	ZKE	96	1000	336.6	336.6	41.3
SN74ALVCH32973KR	LFBGA	GKE	96	1000	336.6	336.6	41.3

GKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY

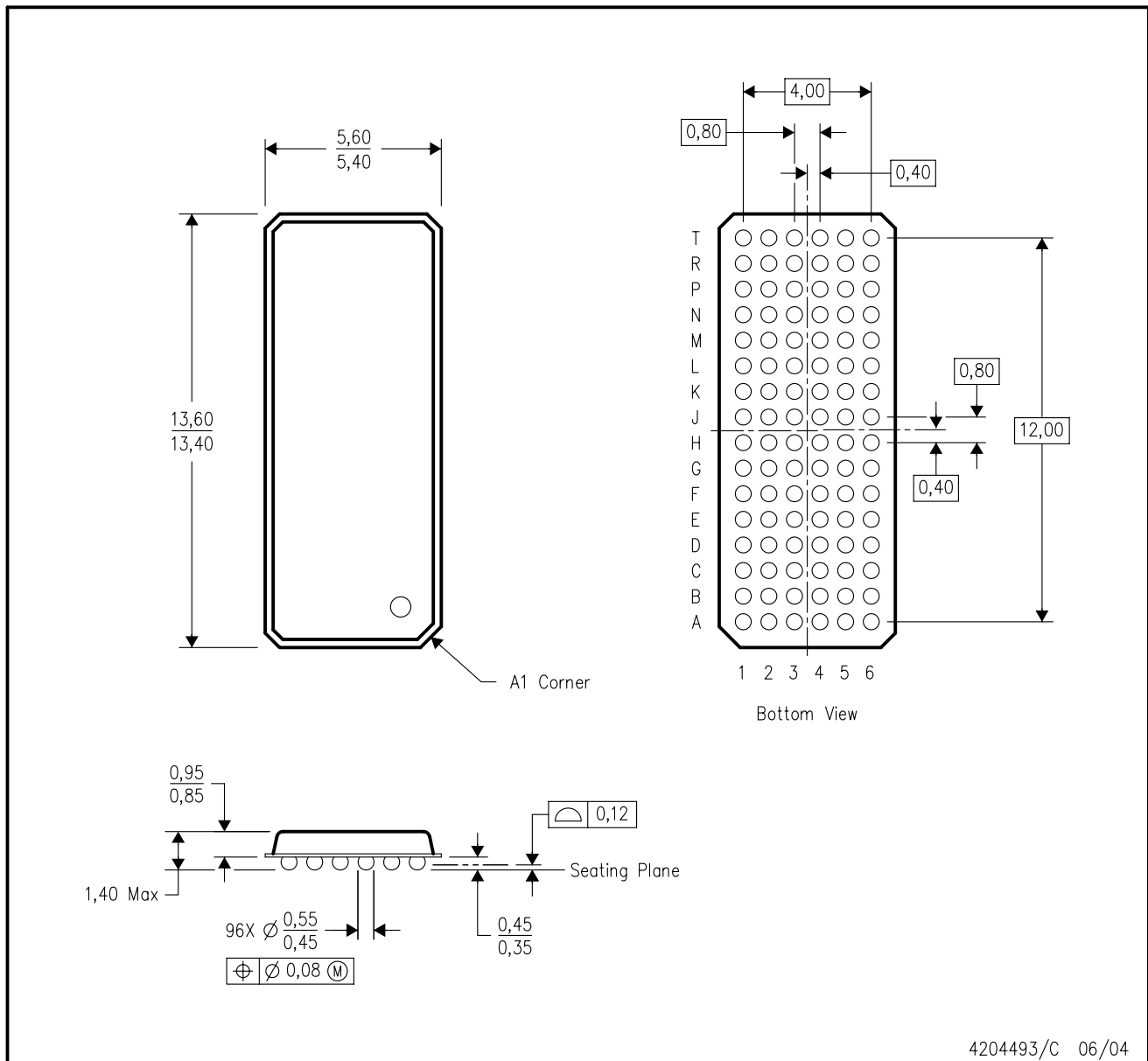


4188953/F 06/04

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

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